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TITLE : PRETREATMENT SOLUTION FOR ELECTROLESS PLATING

ABSTRACT : PURPOSE: To improve the covering power of plating and the adhesive strength of chemical plating by preparing a pretreatment solution by blending inorganic acid, organic acid, metallic complexing agent, and reducing agent with water.

CONSTITUTION: A pretreatment solution for the electroless coppering for printed wiring board, etc., is prepared by blending inorganic acid, organic acid, or a mixture thereof, metallic complexing agent, and reducing agent with water. At this time, hydrochloric acid or sulfuric acid is used as the inorganic acid and oxyacid or keto-acid is used as the organic acid, and further, tartaric acid or its salt, chloride, etc., are used as the metallic complexing agent and formalin, etc., are used as the reducing agent. It is desirable that the contents of the above-mentioned acid, metallic complexing agent, and reducing agent are regulated to about 5.0-60g/l, about 0.3-50g/l, and about 0.3-50g/l, respectively. Since this pretreatment solution has an effect on the inhibition of blow hole occurrence in a punched substrate, the quality of a printed wiring board, etc., can be improved.

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